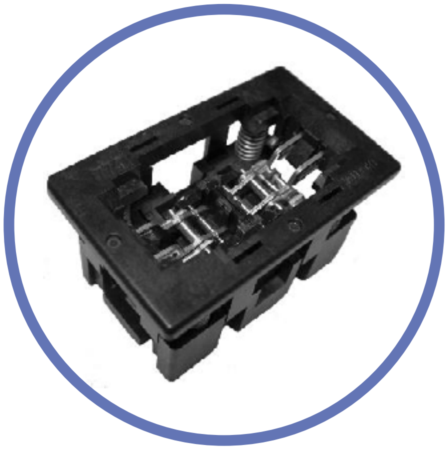
774 SERIES

OPEN TOP CSP



Features

- 0.5mm and 0.8mm pitch
- Compression surface mount
- High performance/low cost achieved through use of carrier loaded stamped contact
- Z-axis compliant buckling beam contact provides stable contact performance independent of solder ball height and compression
- Advanced latch mechanism with flexible pressure pads provides uniformed force distribution across the package surface, enabling the socket to handle up to 900 balls (full 30x30 matrix) and super thin packages.

SPECIFICATIONS

Materials and Specifications

Body Materials	PES, PEI, LCP, or Equivalent
Contact Material	Beryllium Copper Alloy
Contact Plating	Gold
Contact Force	13 grams average
Contact Resistance	200~300 mΩ
Temperature Rating	150°C
Durability	10,000 cycles min.

Pitch e (mm)	Package Size (mm)	Pin. Matrix	Max. Pin Count	Ball Dia. (mm)	Ball Height (mm)	Part Number
0.5	13x10	25x19	475	0.32	0.23	774C4475-XXX
	12x12	23x23	529	0.30	0.21	774C4529-XXX
	15x10	28x19	532	0.30	0.25	774C4532-XXX
	14x14	25x25	625	0.30	0.21	774C4625-XXX
	14x14	26x26	676	0.30	0.20	744C4676-XXX
	14x14	27x27	729	0.30	0.24	774C4729-XXX
	15x15	29x29	841	0.32	0.24	774C4841-XXX
0.8	15x15	17x17	289	0.30	0.15	774N1289-XXX

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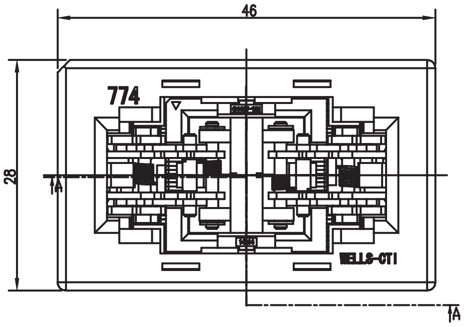
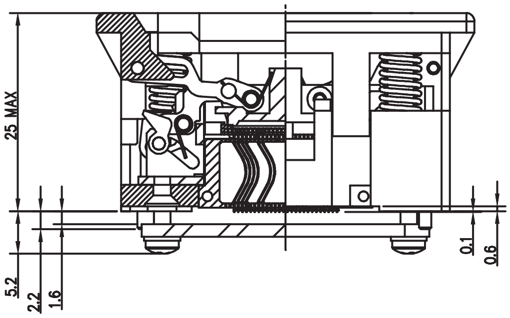
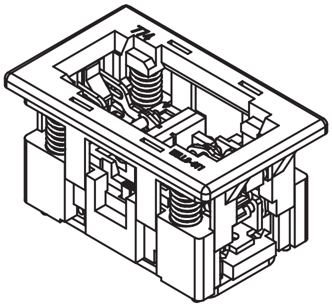
DIMENSIONS AND DIAGRAMS

Dimensions in mm (inches)







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DESCRIPTION & ORDERING INFO

Example : 774 X X XXX-X XX

774 X X XXX - X XX

Series

Package Type

C : 0.5mm pitch U contact
K: 0.5mm pitch LGA contact
P: 0.5mm pitch QFN contact
N: 0.8mm pitch U contact

Pitch

Pin Count

Contact Force Variation

Product Number

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